

## Lonten N-channel 650V, 11A, 0.38Ω LonFET™ Power MOSFET

### Description

LonFET™ Power MOSFET is fabricated using advanced super junction technology. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

### Features

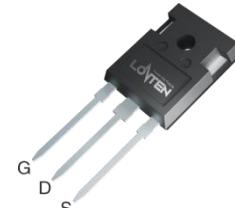
- ◆ Ultra low  $R_{DS(on)}$
- ◆ Ultra low gate charge (typ.  $Q_g = 14.7\text{nC}$ )
- ◆ 100% UIS tested
- ◆ RoHS compliant

### Applications

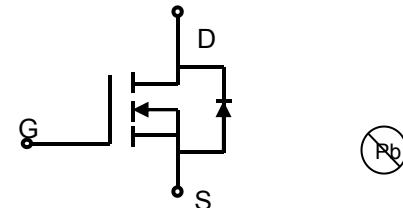
- ◆ Power factor correction (PFC).
- ◆ Switched mode power supplies (SMPS).
- ◆ Uninterruptible power supply (UPS).

### Product Summary

$V_{DS} @ T_{j,max}$	700V
$R_{DS(on),max}$	0.38Ω
$I_{DM}$	30A
$Q_{g,typ}$	14.7 nC



**TO-247**



N-Channel MOSFET

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	650	V
Continuous drain current ( $T_C = 25^\circ\text{C}$ )	$I_D$	11	A
( $T_C = 100^\circ\text{C}$ )		8.2	A
Pulsed drain current <sup>1)</sup>	$I_{DM}$	30	A
Gate-Source voltage	$V_{GSS}$	$\pm 30$	V
Avalanche energy, single pulse <sup>2)</sup>	$E_{AS}$	245	mJ
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	90	W
- Derate above $25^\circ\text{C}$		0.72	$\text{W}/^\circ\text{C}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$
Continuous diode forward current	$I_S$	11	A
Diode pulse current	$I_{S,pulse}$	30	A

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.39	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	45	$^\circ\text{C}/\text{W}$
Soldering temperature, wavesoldering only allowed at leads. (1.6mm from case for 10s)	$T_{sold}$	260	$^\circ\text{C}$

## Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube
LSB65R380HT	TO-247	LSB65R380HT	30

## Electrical Characteristics

$T_c = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static characteristics</b>						
Drain-source breakdown voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=0.25 \text{ mA}$	650	-	-	V
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=0.25 \text{ mA}$	2.5	3.5	4.5	V
Drain cut-off current	$I_{\text{DSS}}$	$V_{\text{DS}}=650 \text{ V}, V_{\text{GS}}=0 \text{ V}, T_j = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
Gate leakage current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}}=30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	100	nA
Gate leakage current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}}=-30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	-100	nA
Drain-source on-state resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=5.5 \text{ A}$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	-	0.33	0.38	$\Omega$
Gate resistance	$R_{\text{G}}$	f=1 MHz, open drain	-	5.7	-	$\Omega$
<b>Dynamic characteristics</b>						
Input capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 100 \text{ V}, V_{\text{GS}} = 0 \text{ V},$ $f = 250 \text{ kHz}$	-	804	-	pF
Output capacitance	$C_{\text{oss}}$		-	36.1	-	
Reverse transfer capacitance	$C_{\text{rss}}$		-	1.35	-	
Turn-on delay time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 400 \text{ V}, I_{\text{D}} = 5.5 \text{ A}$ $R_{\text{G}} = 10\Omega, V_{\text{GS}}=15 \text{ V}$	-	20.6	-	ns
Rise time	$t_r$		-	32	-	
Turn-off delay time	$t_{\text{d(off)}}$		-	62	-	
Fall time	$t_f$		-	12.5	-	
<b>Gate charge characteristics</b>						
Gate to source charge	$Q_{\text{gs}}$	$V_{\text{DD}}=520 \text{ V}, I_{\text{D}}=5.5 \text{ A},$ $V_{\text{GS}}=0 \text{ to } 10 \text{ V}$	-	4.8	-	nC
Gate to drain charge	$Q_{\text{gd}}$		-	4.7	-	
Gate charge total	$Q_g$		-	14.7	-	
Gate plateau voltage	$V_{\text{plateau}}$		-	6	-	
<b>Reverse diode characteristics</b>						
Diode forward voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0 \text{ V}, I_{\text{F}}=5.5 \text{ A}$	-	1.2	-	V
Reverse recovery time	$t_{\text{rr}}$	$V_R=400 \text{ V}, I_{\text{F}}=5.5 \text{ A},$ $dI_{\text{F}}/dt=100 \text{ A}/\mu\text{s}$	-	234	-	ns
Reverse recovery charge	$Q_{\text{rr}}$		-	4.4	-	$\mu\text{C}$
Peak reverse recovery current	$I_{\text{rrm}}$		-	18.7	-	A

### Notes:

- Limited by maximum junction temperature, maximum duty cycle is 0.75.
- $I_{\text{AS}} = 3 \text{ A}, V_{\text{DD}} = 60 \text{ V}$ , Starting  $T_j = 25^\circ\text{C}$ .

## Electrical Characteristics Diagrams

Figure 1. On-Region Characteristics

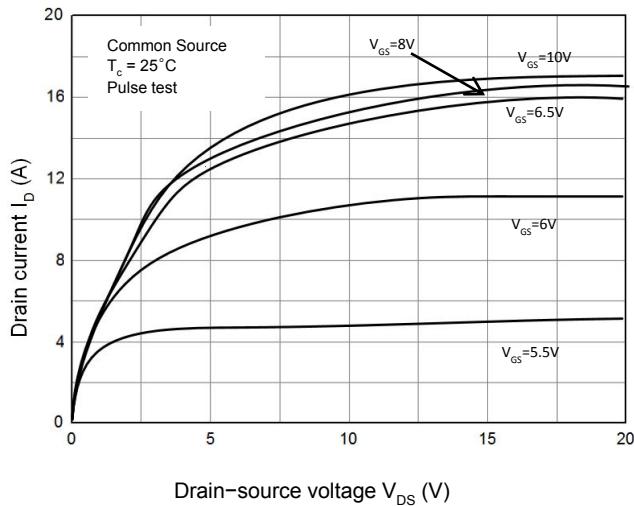


Figure 2. Transfer Characteristics

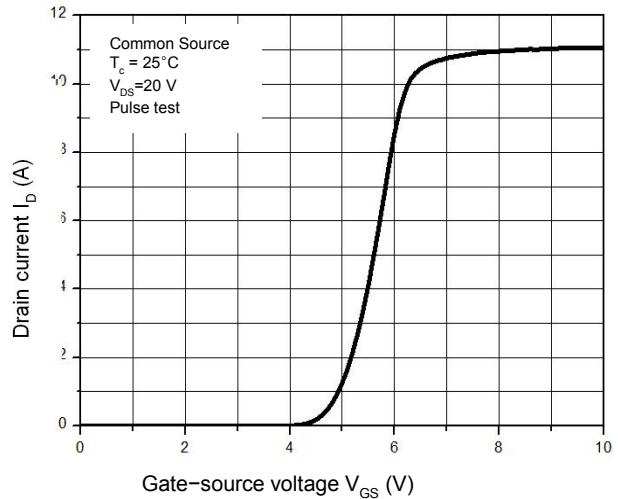


Figure 3. On-Resistance Variation vs. Drain Current

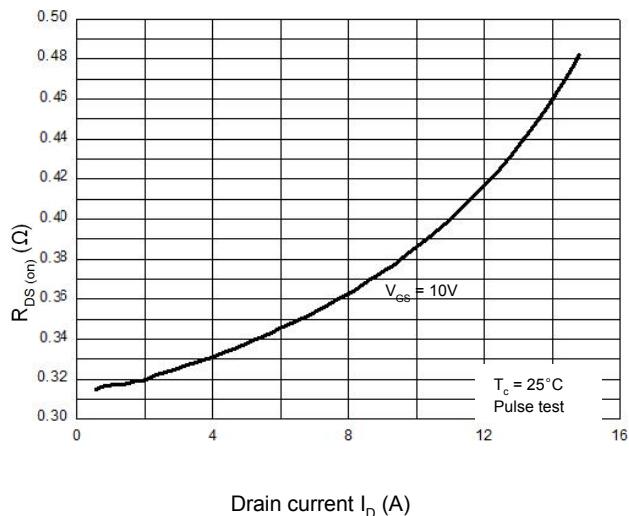


Figure 4. Threshold Voltage vs. Temperature

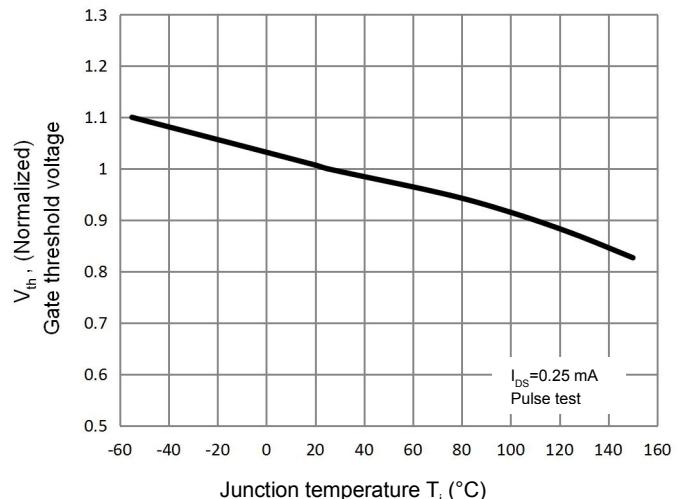


Figure 5. Breakdown Voltage vs. Temperature

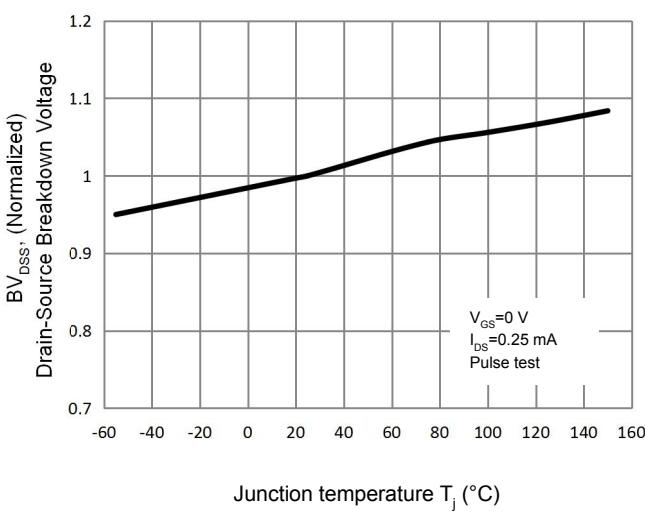


Figure 6. On-Resistance vs. Temperature

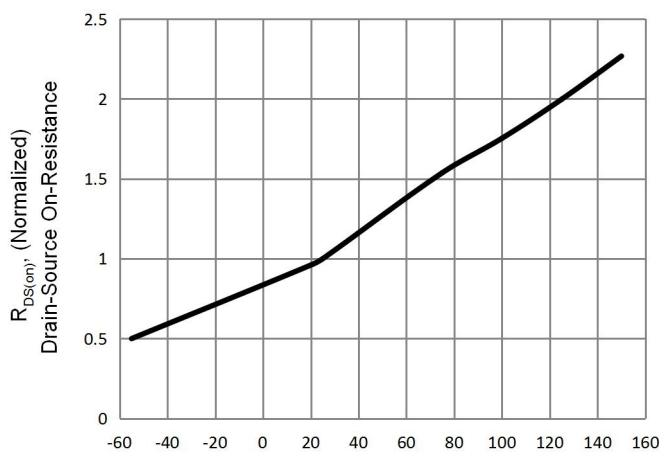


Figure 7. Capacitance Characteristics

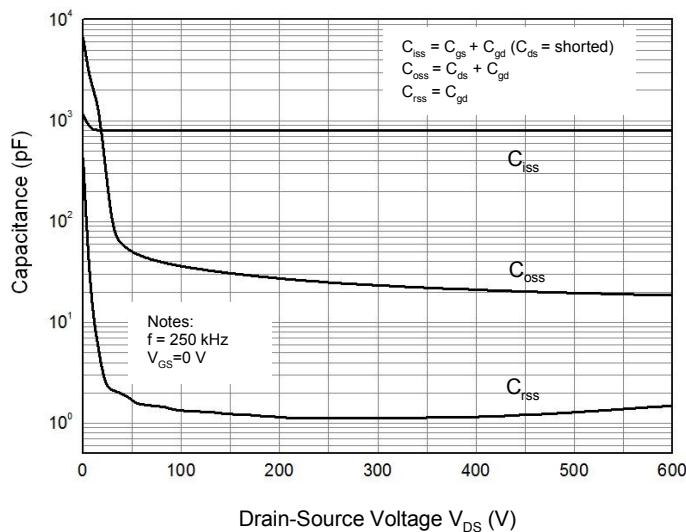


Figure 8. Gate Charge Characteristics

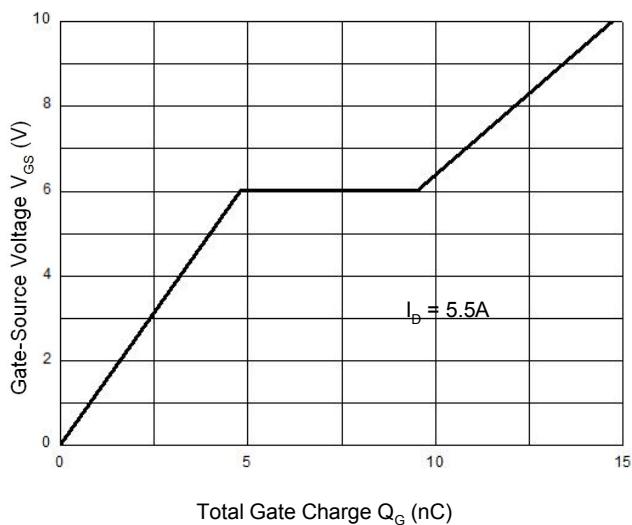


Figure 9. Power Dissipation vs. Temperature

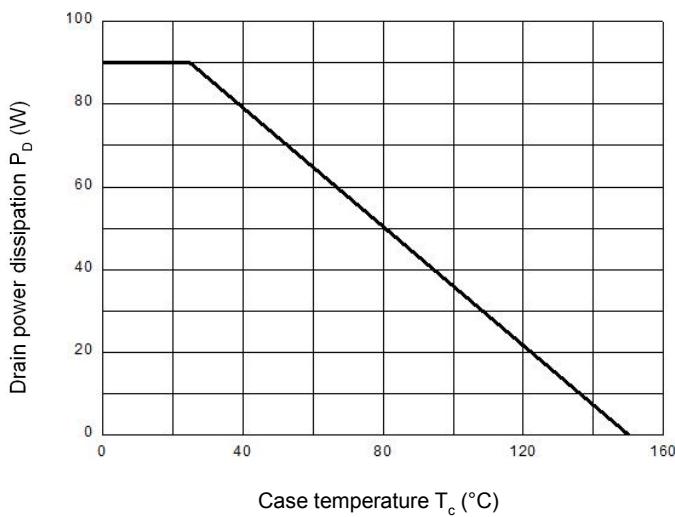


Figure 10. Drain Current Derating

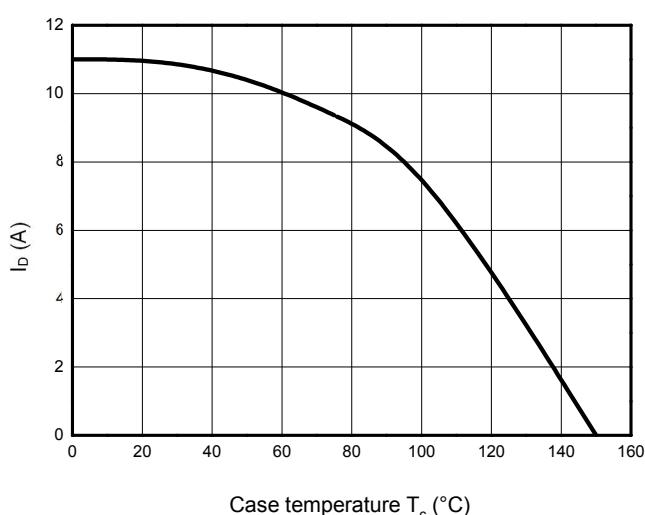


Figure 11: Safe Operating Area

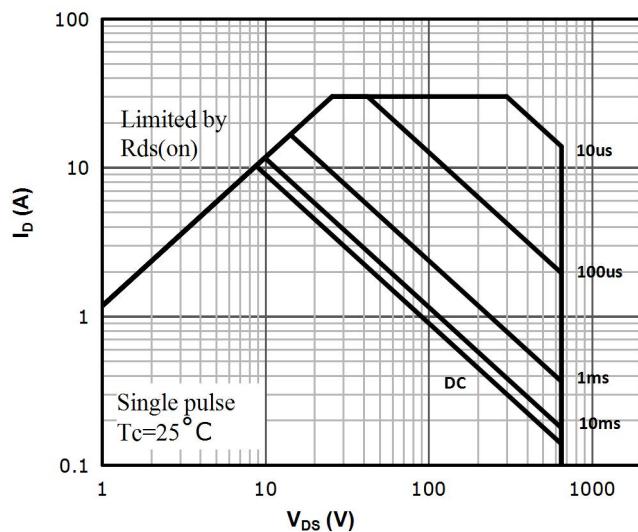
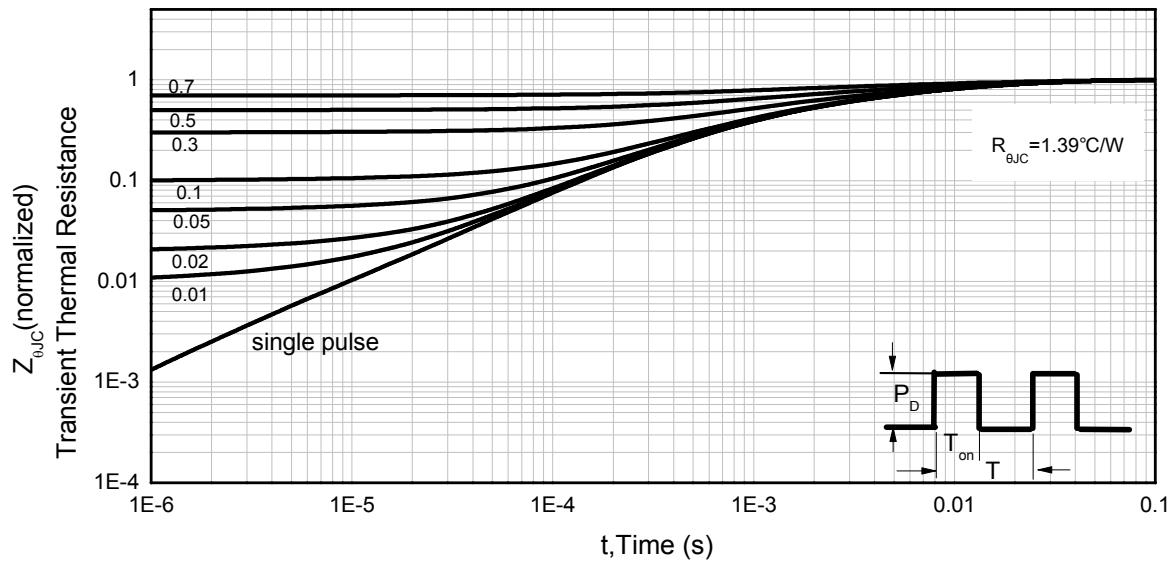
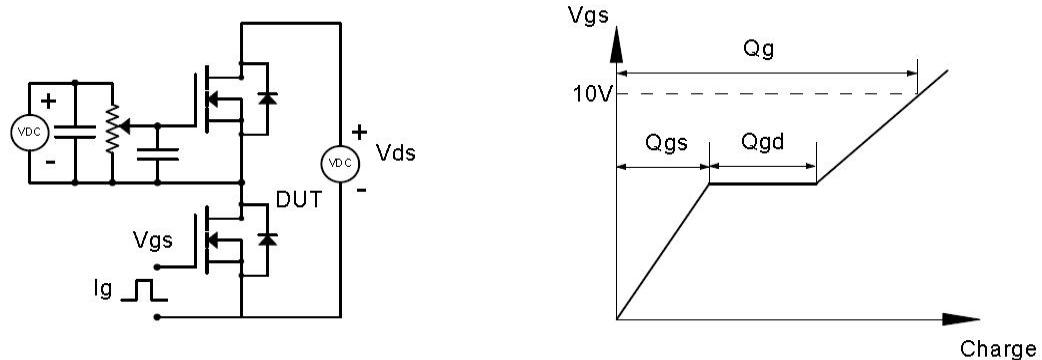


Figure 12. Transient Thermal Response Curve

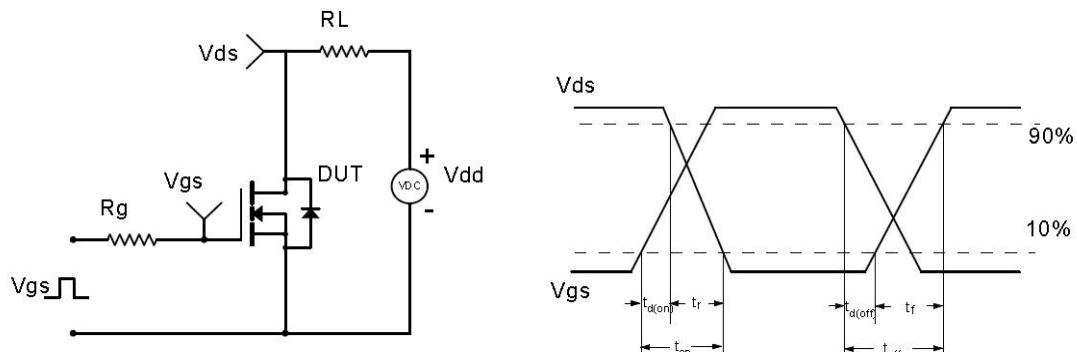


## Test Circuit & Waveform

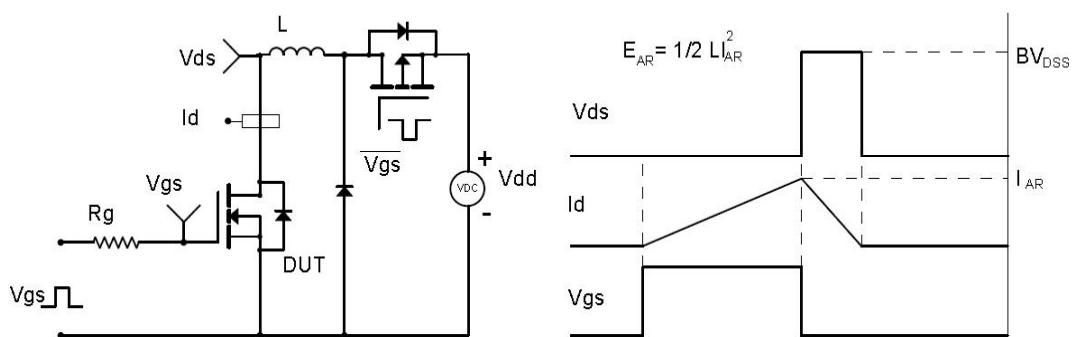
Gate Charge Test Circuit & Waveform



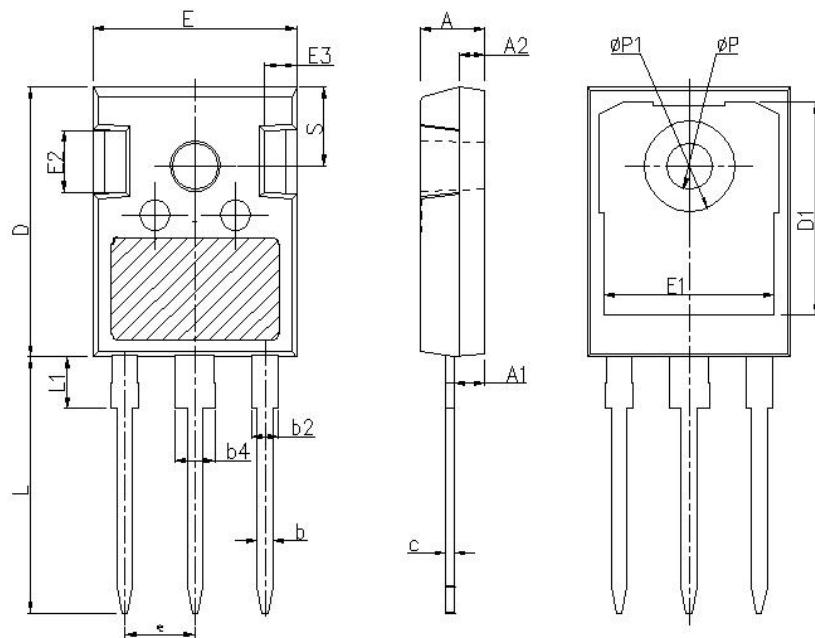
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



## Mechanical Dimensions for TO-247



DIMENSIONS IN MILLIMETERS		DIMENSIONS IN INCHES		
SYMBOL	MIN	MAX	MIN	MAX
A	4. 8	5. 21	0. 189	0. 205
A1	2. 21	2. 61	0. 087	0. 103
A2	1. 85	2. 16	0. 073	0. 085
b	1. 07	1. 36	0. 042	0. 054
b2	1. 91	2. 41	0. 075	0. 095
b4	2. 87	3. 38	0. 113	0. 133
c	0. 51	0. 75	0. 020	0. 030
D	20. 7	21. 3	0. 815	0. 839
D1	16. 25	17. 65	0. 640	0. 695
E	15. 5	16. 13	0. 610	0. 635
E1	13	13. 6	0. 512	0. 535
E2	3. 68	5. 2	0. 145	0. 205
E3	1	2. 7	0. 039	0. 106
e	5. 44BSC		0. 214BSC	
L	19. 62	20. 32	0. 772	0. 800
L1	-	4. 4	-	0. 173
ΦP	3. 4	3. 8	0. 134	0. 150
ΦP1	-	7. 4	-	0. 291
S	6. 04	6. 3	0. 238	0. 248

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